ERICSSON

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PBL 386 30/2 Subscriber Line Interface Circuit

Description

The PBL 386 30/2 Subscriber Line Interface Circuit (SLIC) is a 90 V bipolar integrated circuit for use in Digital Loop Carrier, FITL and other telecommunications equipment. The PBL 386 30/2 has been optimized for low total line interface cost and a high degree of flexibility in different applications.

The PBL 386 30/2 emulates resistive loop feed, programmable between 2x50 Ω and 2x900 Ω, with short loop current limiting adjustable to max 45 mA. In the current limited region the loop feed is nearly constant current with a slight slope corresponding to 2x30kΩ.

A second lower battery voltage may be connected to the device to reduce short loop power dissipation. The SLIC automatically switches between the two battery supply voltages without need for external components or external control.

The SLIC incorporates loop current and ring trip detection functions. The PBL 386 30/2 is compatible with loop start signaling.

Two- to four-wire and four- to two-wire voice frequency (VF) signal conversion is accomplished by the SLIC in conjunction with either a conventional CODEC/filter or with a programmable CODEC/filter, e.g. SLAC, SiCoFi, Combo II. The programmable two-wire impendance, complex or real, is set by a simple external network.

Longitudinal voltages are suppressed by a feedback loop in the SLIC and the longitudinal balance specifications meet the DLC requirements.

The PBL 386 30/2 package options are 24-pin SSOP, 24-pin SOIC and 28-pin PLCC.

Key Features

- 24-pin SSOP package
- High and low battery supply with automatic switching
- 65 mW on-hook power dissipation in active state
- On-hook transmission
- Long loop battery feed tracks Vbat for maximum line voltage
- Only +5 V feed in addition to battery
- Selectable transmit gain (1x or 0.5x)
- No power-up sequence
- Programmable signal headroom
- 43V open loop voltage @ -48V battery feed
- Constant loop voltage for line leakage <5 mA (RLeak ~ >10 kΩ @ -48V)
- Full longitudinal current capability during on-hook state
- Analog over temperature protection permits transmission while the protection circuit is active
- Integrated Ring Relay Driver
- -40°C to +85°C ambient temperature range

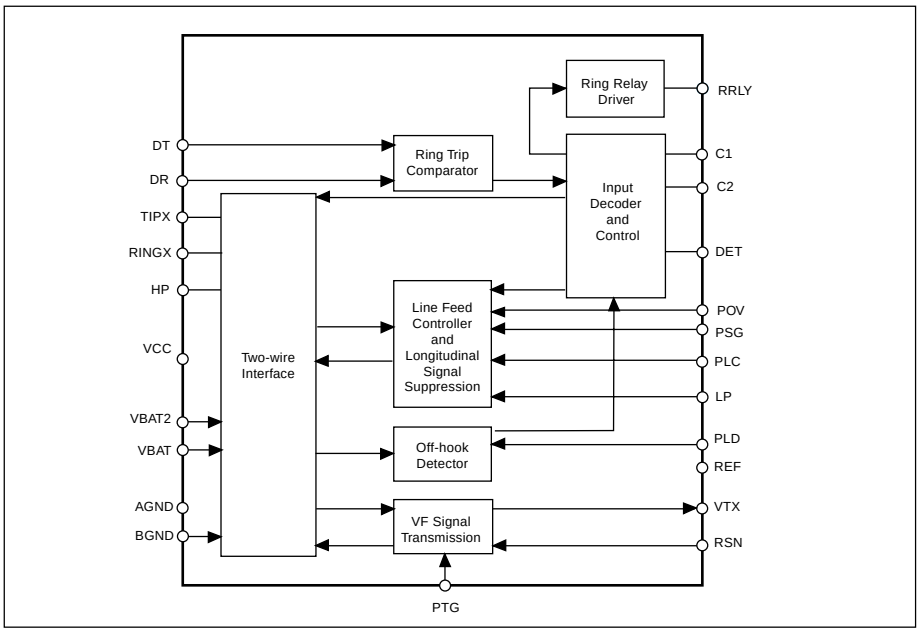
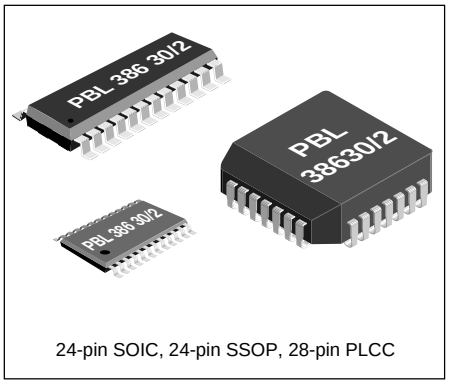


Figure 1. Block diagram.



24-pin SOIC, 24-pin SSOP, 28-pin PLCC

Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Temperature, Humidity				
Storage temperature range	T_{Stg}	-55	+150	°C
Operating temperature range	T_{Amb}	-40	+110	°C
Operating junction temperature range, Note 1	T_J	-40	+140	°C
Power supply, -40 °C ≤ T_{Amb} ≤ +85 °C				
V_{CC} with respect to A/BGND	V_{CC}	-0.4	6.5	V
V_{Bat2} with respect to A/BGND	V_{Bat2}	V_{Bat}	0.4	V
V_{Bat} with respect to A/BGND, continuous	V_{Bat}	-75	0.4	V
V_{Bat} with respect to A/BGND, 10 ms	V_{Bat}	-80	0.4	V
Power dissipation				
Continuous power dissipation at T_{Amb} ≤ +85 °C	P_D		1.5	W
Ground				
Voltage between AGND and BGND	V_G	-0.3	0.3	V
Relay Driver				
Ring relay supply voltage			BGND+14	V
Ring trip comparator				
Input voltage	V_{DT}, V_{DR}	V_{Bat}	AGND	V
Input current	I_{DT}, I_{DR}	-5	5	mA
Digital inputs, outputs (C1, C2, DET)				
Input voltage	V_{ID}	-0.4	V_{CC}	V
Output voltage	V_{OD}	-0.4	V_{CC}	V
TIPX and RINGX terminals, -40°C < T_{Amb} < +85°C, V_{Bat} = -50V				
Maximum supplied TIPX or RINGX current	I_{TIPX}, I_{RINGX}	-100	+100	mA
TIPX or RINGX voltage, continuous (referenced to AGND), Note 2	V_{TA}, V_{RA}	-80	2	V
TIPX or RINGX, pulse < 10 ms, t_{Rep} > 10 s, Note 2	V_{TA}, V_{RA}	V_{Bat} -10	5	V
TIPX or RINGX, pulse < 1 µs, t_{Rep} > 10 s, Note 2	V_{TA}, V_{RA}	V_{Bat} -25	10	V
TIPX or RINGX, pulse < 250 ns, t_{Rep} > 10 s, Notes 2 & 3	V_{TA}, V_{RA}	V_{Bat} -35	15	V

Recommended Operating Condition

Parameter	Symbol	Min	Max	Unit
Ambient temperature	T_{Amb}	-40	+85	°C
V_{CC} with respect to AGND	V_{CC}	4.75	5.25	V
V_{Bat} with respect to AGND	V_{Bat}	-58	-8	V
AGND with respect to BGND	V_G	-100	100	mV

Notes

1. The circuit includes thermal protection. Operation at or above 140°C junction temperature may degrade device reliability.
2. With the diodes D_{VB} and D_{VB2} included, see figure 11.
3. R_{F1} and R_{F2} ≥ 20 Ω is also required. Pulse is applied to TIP and RING outside R_{F1} and R_{F2}.

Electrical Characteristics

-40 °C ≤ T_{Amb} ≤ +85 °C, PTG = open (see pin description), V_{CC} = +5V ±5 %, V_{Bat} = -58V to -40V, V_{Bat2} = -32 V, R_{LC}=32.4 kΩ, I_L = 27 mA. R_L = 600 Ω, R_{F1}= R_{F2} = 0, R_{Ref} = 49.9 kΩ, C_{HP} = 47 nF, C_{LP}=0.15 µF, R_T = 120 kΩ, R_{SG} = 0 kΩ, R_{RX} = 60 kΩ, R_R = 52.3 kΩ R_{OV} = ∞, unless otherwise specified. Current definition: current is positive if flowing into a pin.

Parameter	Ref fig	Conditions	Min	Typ	Max	Unit
Two-wire port						
Overload level, V_{TRO} ,I_{Ldc} ≥ 18mA	2	Active state,				
		1% THD, R_{OV} = ∞	2.7			V_{Peak}
On-Hook, I_{Ldc} ≤ 5mA		Note 1	1.1			V_{Peak}
Input impedance, Z_{TR}		Note 2		Z_T/200		
Longitudinal impedance, Z_{LOT}, Z_{LOR}		0 < f < 100 Hz		20	35	Ω/wire
Longitudinal current limit, I_{LOT}, I_{LOR}		active state	28			mA_{rms}/wire
Longitudinal to metallic balance, B_{LM}		IEEE standard 455-1985, Z_{TRX}=736Ω				
		0.2 kHz < f < 1.0 kHz, T_{amb} 0-70°C	63	66		dB
		1.0 kHz < f < 3.4 kHz, T_{amb} 0-70°C	60	66		dB
		0.2 kHz < f < 1.0 kHz, T_{amb} -40-85°C	60	66		dB
		1.0 kHz < f < 3.4 kHz, T_{amb} -40-85°C	55	66		dB
Longitudinal to metallic balance, B_{LME}	3					
Longitudinal to four wire balance B_{LFE}	3	0.2 kHz < f < 1.0 kHz, T_{amb} 0-70°C	63	66		dB
		1.0 kHz < f < 3.4 kHz, T_{amb} 0-70°C	60	66		dB
$B_{LME} = 20 \cdot Log\left\lvert\frac{E_{Lo}}{V_{TR}}\right\rvert$		0.2 kHz ≤ f ≤ 1.0 kHz, T_{amb} -40-85°C	60	66		dB
		1.0 kHz < f < 3.4 kHz, T_{amb} -40-85°C	55	66		dB
$B_{LFE} = 20 \cdot Log\left\lvert\frac{E_{Lo}}{V_{TX}}\right\rvert$						
Metallic to longitudinal balance, B_{MLE}	4	0.2 kHz < f < 3.4 kHz	40	50		dB
$B_{MLE} = 20 \cdot Log\left\lvert\frac{V_{TR}}{V_{LO}}\right\rvert$; E_{RX} = 0						

Figure 2. Overload level, V_{TRO} , two-wire port

$\frac{1}{\omega C}$ << R_L, R_L= 600 Ω

R_T = 120 kΩ, R_{RX} = 60 kΩ

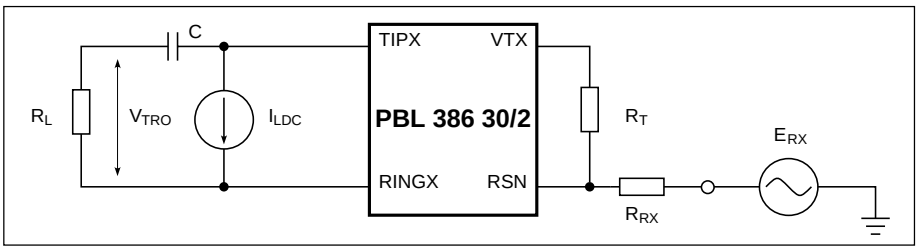
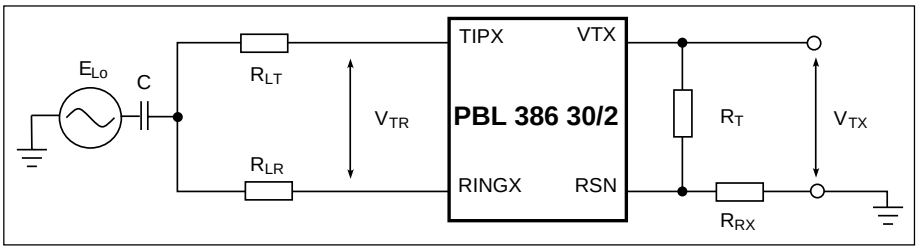


Figure 3. Longitudinal to metallic (B_{LME}) and Longitudinal to four-wire (B_{LFE}) balance

$\frac{1}{\omega C}$ << 150 Ω, R_{LR}=R_{LT} =R_L /2=300Ω

R_T = 120 kΩ, R_{RX} = 60 kΩ



Parameter	Ref fig	Conditions	Min	Typ	Max	Unit
Four-wire to longitudinal balance, B_{FLE}	4	0.2 kHz < f < 3.4 kHz $B_{FLE} = 20 \cdot Log \left\lvert \frac{E_{RX}}{V_{Lo}} \right\rvert$	40	50		dB
Two-wire return loss, r		$r = 20 \cdot Log \frac{\lvert Z_{TR} + Z_L \rvert}{\lvert Z_{TR} - Z_L \rvert}$				
		0.2 kHz < f < 1.0 kHz	30	35		dB
		1.0 kHz < f < 3.4 kHz, Note 3	20	22		dB
TIPX idle voltage, V_{Ti}		active, I_L < 5 mA		- 1.3		V
RINGX idle voltage, V_{Ri}		active, I_L < 5 mA		V_{Bat} +3.0		V
V_{TR}		active, I_L < 5 mA		V_{Bat} +4.3		V
Four-wire transmit port (VTX)						
Overload level, V_{TXO}, $I_L \geq$ 18mA	5	Load impedance > 20 kΩ, 1% THD, Note 4	2.7			V_{Peak}
On-hook, $I_L \leq$ 5mA			1.1			V_{Peak}
Output offset voltage, ΔV_{TX}			-100	0	100	mV
Output impedance, z_{TX}		0.2 kHz < f < 3.4 kHz		15	50	Ω
Four-wire receive port (RSN)						
Receive summing node (RSN) DC voltage		I_{RSN} = -55 µA	1.15	1.25	1.35	V
Receive summing node (RSN) impedance		0.2 kHz < f < 3.4 kHz		8	20	Ω
Receive summing node (RSN) current (I_{RSN}) to metallic loop current (I_L) gain, α_{RSN}		0.3 kHz < f < 3.4 kHz		200		ratio
Frequency response						
Two-wire to four-wire, g_{2-4}	6	relative to 0 dBm, 1.0 kHz. E_{RX} = 0 V				
		0.3 kHz < f < 3.4 kHz	-0.20		0.10	dB
		f = 8.0 kHz, 12 kHz, 16 kHz	-1.0		0.1	dB

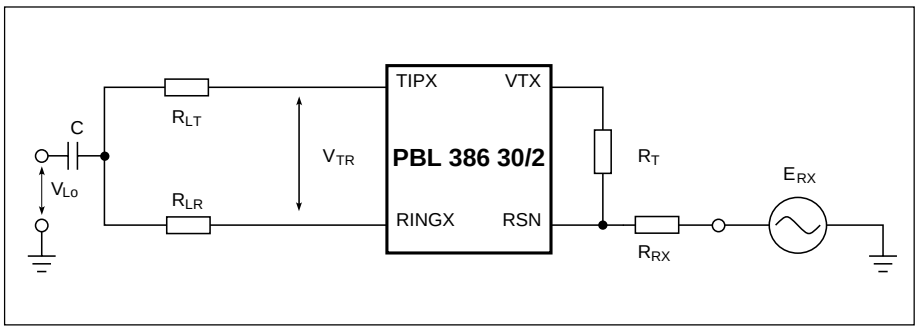


Figure 4. Metallic to longitudinal and four-wire to longitudinal balance

$\frac{1}{\omega C}$ << 150 Ω, $R_{LT} = R_{LR} = R_L/2 = 300\Omega$

R_T = 120 kΩ, R_{RX} = 60 kΩ

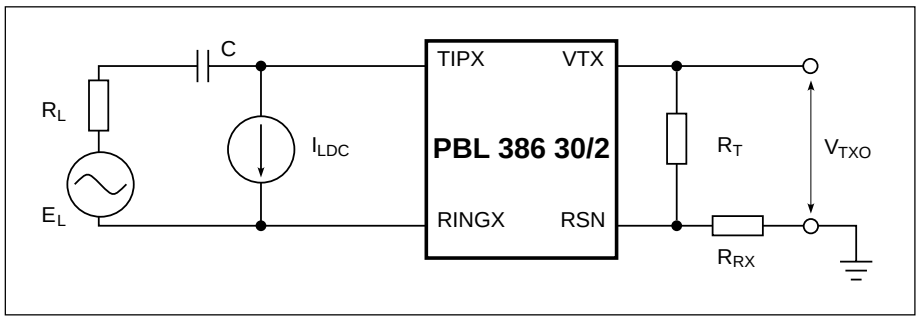


Figure 5. Overload level, V_{TXO}, four-wire transmit port

$\frac{1}{\omega C}$ << R_L, R_L = 600 Ω

R_T = 120 kΩ, R_{RX} = 60 kΩ

Parameter	Ref fig	Conditions	Min	Typ	Max	Unit
Four-wire to two-wire, g_{4-2}	6	relative to 0 dBm, 1.0 kHz. E_L=0 V				
		0.3 kHz < f < 3.4 kHz	-0.2		0.1	dB
		f = 8 kHz, 12 kHz,	-1.0		0	dB
		16 kHz	-2.0		0	dB
Four-wire to four-wire, g_{4-4}	6	relative to 0 dBm, 1.0 kHz, E_L=0 V				
		0.3 kHz < f < 3.4 kHz	-0.2		0.1	dB
Insertion loss						
Two-wire to four-wire, G_{2-4}	6	0 dBm, 1.0 kHz, Note 5				
		$G_{2-4} = 20 \cdot \text{Log}\left\lvert\frac{V_{TX}}{V_{TR}}\right\rvert$; $E_{RX} = 0$	-0.2		0.2	dB
		PTG = AGND	-6.22	-6.02	-5.82	dB
Four-wire to two-wire, G_{4-2}	6	0 dBm, 1.0 kHz, Note 6				
		$G_{4-2} = 20 \cdot \text{Log}\left\lvert\frac{V_{TR}}{E_{RX}}\right\rvert$; $E_L = 0$	-0.2		0.2	dB
Gain tracking						
Two-wire to four-wire	6	Ref. -10 dBm, 1.0 kHz, Note 7				
		-40 dBm to +3 dBm	-0.1		0.1	dB
		-55 dBm to -40 dBm	-0.2		0.2	dB
Four-wire to two-wire	6	Ref. -10 dBm , 1.0 kHz				
		-40 dBm to +3 dBm	-0.1		0.1	dB
		-55 dBm to -40 dBm	-0.2		0.2	dB
Noise						
Idle channel noise at two-wire		C-message weighting			12	dBrnC
(TIPX-RINGX) or four-wire (VTX) output		Psophometrical weighting			-78	dBmp
		Note 8				
Harmonic distortion						
Two-wire to four-wire	6	0 dBm		-67	-50	dB
Four-wire to two-wire		0.3 kHz < f < 3.4 kHz		-67	-50	dB
Battery feed characteristics						
Loop current, I_L , in the current limited region, reference A, B & C	12	18mA ≤ I_L ≤ 45 mA	0.92 I_L	I_L	1.08 I_L	mA
Open circuit state loop current, I_{LOC}		R_L = 0Ω	-100	0	100	µA

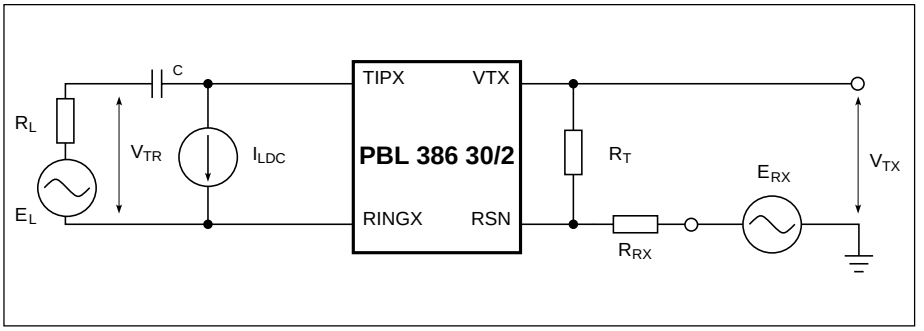


Figure 6.
Frequency response, insertion loss, gain tracking.

$\frac{1}{\omega C} << R_L$, R_L = 600 kΩ

R_T = 120 kΩ, R_{RX} = 60 kΩ

Parameter	Ref fig	Conditions	Min	Typ	Max	Unit
Loop current detector						
Programmable threshold, I_{LTh}		$I_{LTh} = \frac{500}{R_{LD}}$ R_{LD} in kΩ, $I_{LTh} \geq 7$ mA	$0.85 \cdot I_{LTh}$	I_{LTh}	$1.15 \cdot I_{LTh}$	mA
Ring trip comparator						
Offset voltage, ΔV_{DTDR}		Source resistance, $R_S = 0\ \Omega$	-20	0	20	mV
Input bias current, I_B		$I_B = (I_{DT} + I_{DR})/2$	-200	-20	200	nA
Input common mode range, V_{DT}, V_{DR}			$V_{Bat}+1$		-1	V
Ring relay driver						
Saturation voltage, V_{OL}		I_{OL} = 50 mA		0.2	0.5	V
Off state leakage current, I_{Lk}		V_{OH} = 12 V			10	µA
Digital inputs (C1, C2)						
Input low voltage, V_{IL}			0		0.5	V
Input high voltage, V_{IH}			2.5		V_{CC}	V
Input low current, I_{IL}		V_{IL} = 0.5			-50	µA
Input high current, I_{IH}		V_{IH} = 2.5 V			50	µA
Detector output (DET)						
Output low voltage		I_{OL} = 0.5 mA			0.7	V
Internal pull-up resistor				15		kΩ
Power dissipation (V_{Bat} = -48V,V_{Bat2} = -32V)						
P_1		Open circuit state, C1, C2 = 0, 0		10	15	mW
		Active state, C1, C2 = 0, 1				
P_2		Longitudinal current = 0 mA, I_L=0 mA (on-hook)		65	85	mW
P_3		R_L =300Ω (off-hook)		730		mW
P_4		R_L =800Ω (off-hook)		360		mW
Power supply currents (V_{Bat} = -48V)						
V_{CC} current, I_{CC}		Open circuit state		1.2	2.0	mA
V_{Bat} current, I_{Bat}			-0.10	-0.05		mA
V_{CC} current, I_{CC}		Active state		2.8	4.0	mA
V_{Bat} current, I_{Bat}		On-hook, Long Current = 0 mA	-1.5	-1.0		mA
Power supply rejection ratios						
V_{CC} to 2- or 4-wire port		Active State	30	42		dB
V_{Bat} to 2- or 4-wire port		f= 1kHz, V_n = 100mV	36	45		dB
V_{Bat2} to 2- or 4-wire port			40	60		dB
Temperature guard						
Junction threshold temperature, T_{JG}				145		°C
Thermal resistance						
28-pin PLCC, $\theta_{JP28plcc}$				39		°C/W
24-pin SOIC, $\theta_{JP24soic}$				43		°C/W
24-pin SSOP, $\theta_{JP24ssop}$				55		°C/W

Notes

1. The overload level can be adjusted with the R_{OV} resistor for higher levels e.g. min 3.1 V_{Peak} and is specified at the two-wire port with the signal source at the four-wire receive port.
2. The two-wire impedance is programmable by selection of external component values according to:
   $Z_{TRX} = Z_T/|G_{2-4S}\,\alpha_{RSN}|$ where:
   Z_{TRX} = impedance between the TIPX and RINGX terminals
   Z_T = programming network between the VTX and RSN terminals
   G_{2-4S} = transmit gain, nominally = 1 (or 0.5 see pin PTG)
   α_{RSN} = receive current gain, nominally = 200 (current defined as positive flowing into the receivesumming node, RSN, and when flowing from ring to tip).
3. Higher return loss values can be achieved by adding a reactive component to R_T, the two-wire terminating impedance programming resistance, e.g. by dividing R_T into two equal halves and connecting a capacitor from the common point to ground.
4. The overload level level can be adjusted with the R_{OV} resistor for higher levels e.g. min 3.1 V_{Peak} and is specified at the four-wire transmit port, VTX, with the signal source at the two-wire port. Note that the gain from the two-wire port to the four-wire transmit port is G_{2-4S} = 1 (or 0.5 see pin PTG)
5. Pin PTG = Open sets transmit gain to nom. 0.0dB
   Pin PTG = AGND sets transmit gain to nom. -6.02 dB
   Secondary protection resistors R_F impact the insertion loss as explained in the text, section Transmission. The specified insertion loss is for $R_F = R_P = 0$.
6. The specified insertion loss tolerance does not include errors caused by external components.
7. The level is specified at the two-wire port.
8. The two-wire idle noise is specified with the port terminated in 600 Ω (R_L) and with the four-wire receive port grounded (E_{RX} = 0; see figure 6).
   The four-wire idle noise at VTX is specified with the two-wire port terminated in 600 Ω (R_L). The noise specification is referenced to a 600 Ω programmed two-wire impedance level at VTX. The four-wire receive port is grounded (E_{RX} = 0).

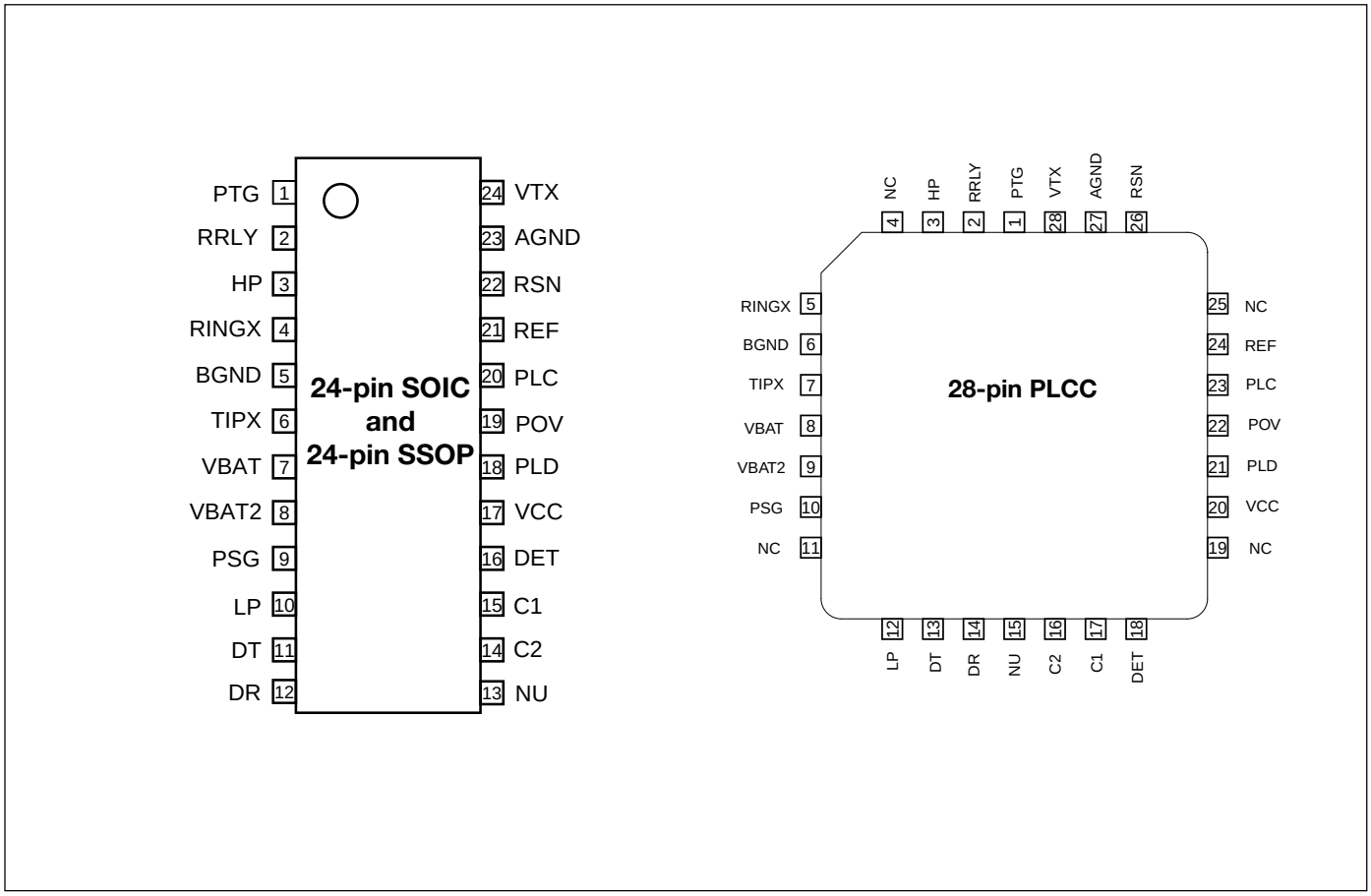


Figure 7. Pin configuration, 24-pin SSOP, 24-pin SOIC and 28 pin PLCC package, top view.

Pin Description

Refer to figure 7.

PLCC	Symbol	Description
1	PTG	**P**rog. **T**ransmit **G**ain. Left open transmit gain = 0.0 dB, connected to AGND transmit gain = -6.02 dB.
2	RRLY	**R**ing **Re**l**ay** driver output. The relay coil may be connected to maximum +14V.
3	HP	Connection for **H**igh **P**ass filter capacitor, C_{HP}. Other end of C_{HP} connects to TIPX.
4	NC	**N**o internal **C**onnection
5	RINGX	The TIPX and RINGX pins connect to the tip and ring leads of the two-wire interface via overvoltage protection components and ring relay (and optional test relay).
6	BGND	**B**attery **G**rou**nd**, should be tied together with AGND.
7	TIPX	The TIPX and RINGX pins connect to the tip and ring leads of the two-wire interface via overvoltage protection components and ring relay (and optional test relay).
8	VBAT	**Bat**tery supply **V**oltage. Negative with respect to AGND.
9	VBAT2	An optional second (2) **Bat**tery **V**oltage connects to this pin.
10	PSG	**P**rogrammable **S**aturation **G**uard. The resistive part of the DC feed characteristic is programmed by a resistor connected from this pin to VBAT.
11	NC	**N**o internal **C**onnection
12	LP	Connection for **L**ow **P**ass filter capacitor, C_{LP}. Other end of C_{LP} connects to VBAT.
13	DT	Input to the ring trip comparator. With DR more positive than DT the detector output, DET, is at logic level low, indicating off-hook condition. The external ring trip network connects to this input.
14	DR	Input to the ring trip comparator. With DR more positive than DT the detector output, DET, is at logic level low, indicating off-hook condition. The external ring trip network connects to this input.

15	NU	Pin **N**ot **U**sed. Must be connected to AGND.
16 17	C2 C1	C1 and C2 are digital inputs (internal pull-up) controlling the SLIC operating states. Refer to section "Operating states" for details.
18	DET	**Det**ector output. Active low when indicating loop detection and ring trip.
19	NC	**N**o internal **C**onnection
20	VCC	+5 V power supply.
21	PLD	**P**rogrammable **L**oop **D**etector threshold. The loop detection threshold is programmed by a resistor connected from this pin to AGND.
22	POV	**P**rogrammable **O**verhead **V**oltage. If pin is left open: The overhead voltage is internally set to min 2.7 V in off-hook and min 1.1 V in On-hook. If a resistor is connected between this pin and AGND: the overhead voltage can be set to higher values.
23	PLC	**P**rog. **L**ine **C**urrent, the current limit, reference C in figure 12, is programmed by a resistor connected from this pin to AGND.
24	REF	A **Ref**erence, 49.9 kΩ, resistor should be connected from this pin to AGND.
25	NC	**N**o internal **C**onnection
26	RSN	**R**eceive **S**umming **N**ode. 200 times the AC-current flowing into this pin equals the metallic (transversal) AC-current flowing from RINGX to TIPX. Programming networks for two-wire impedance and receive gain connect to the receive summing node. A resistor should be connected from this pin to AGND.
27	AGND	Analog Ground, should be tied together with BGND.
28	VTX	Transmit vf output. The AC voltage difference between TIPX and RINGX, the AC metallic voltage, is reproduced as an unbalanced GND referenced signal at VTX with a gain of one (or one half, see pin PTG). The two-wire impedance programming network connects between VTX and RSN.

SLIC Operating States

State	C2	C1	SLIC operating state	Active detector
0	0	0	Open circuit	-
1	0	1	Ringing state	Ring trip detector (active low)
2	1	0	Active state	Loop detector (active low)
3	1	1	Not applicable	-

Table 1. SLIC operating states.

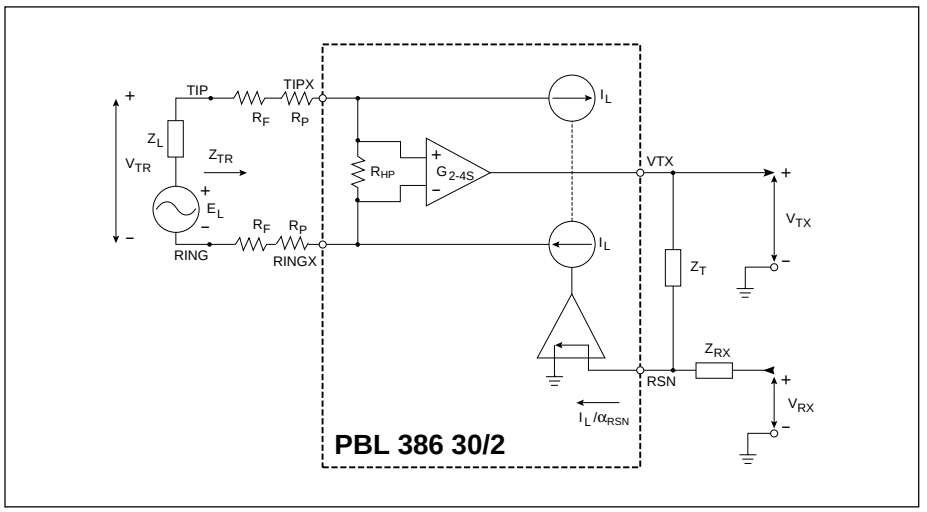


Figure 8. Simplified ac transmission circuit.

Functional Description and Applications Information

Transmission

General

A simplified ac model of the transmission circuits is shown in figure 8. Circuit analysis yields:

$$V_{TR} = \frac{V_{TX}}{G_{2-4S}} + I_L \cdot (2R_F + 2R_P) \quad (1)$$

$$\frac{V_{TX}}{Z_T} + \frac{V_{RX}}{Z_{RX}} = \frac{I_L}{\alpha_{RSN}} \quad (2)$$

$$V_{TR} = E_L - I_L \cdot Z_L \quad (3)$$

where:

- V_{TX} is a ground referenced version of the ac metallic voltage between the TIPX and RINGX terminals.
- $G_{2\text{-}4S}$ is the programmable SLIC two-wire to four-wire gain (transmit direction). See note below.
- V_{TR} is the ac metallic voltage between tip and ring.
- E_L is the line open circuit ac metallic voltage.
- I_L is the ac metallic current.
- R_F is a fuse resistor.
- R_P is part of the SLIC protection
- Z_L is the line impedance.
- Z_T determines the SLIC TIPX to RINGX impedance at voice frequencies.
- Z_{RX} controls four- to two-wire gain.
- V_{RX} is the analog ground referenced receive signal.
- α_{RSN} is the receive summing node current to metallic loop current gain = 200.

Note that the SLICs two-wire to four-wire gain, $G_{2\text{-}4S}$, is user programmable between two fix values. Refer to the datasheets for values on $G_{2\text{-}4S}$.

Two-Wire Impedance

To calculate Z_{TR}, the impedance presented to the two-wire line by the SLIC including the fuse and protection resistors R_F and R_P, let:

$V_{RX} = 0$.

From (1) and (2):

$$Z_{TR} = \frac{Z_T}{\alpha_{RSN} \cdot G_{2-4S}} + 2R_F + 2R_P$$

Thus with Z_{TR}, α_{RSN}, $G_{2\text{-}4S}$, R_P and R_F known:

$$Z_T = \alpha_{RSN} \cdot G_{2-4S} \cdot (Z_{TR} - 2R_F - 2R_P)$$

Two-Wire to Four-Wire Gain

From (1) and (2) with $V_{RX} = 0$:

$$G_{2-4} = \frac{V_{TX}}{V_{TR}} = \frac{Z_T / \alpha_{RSN}}{\frac{Z_T}{\alpha_{RSN} \cdot G_{2-4S}} + 2R_F + 2R_P}$$

Four-Wire to Two-Wire Gain

From (1), (2) and (3) with $E_L = 0$:

$$G_{4-2} = \frac{V_{TR}}{V_{RX}} = -\frac{Z_T}{Z_{RX}} \cdot \frac{Z_L}{\frac{Z_T}{\alpha_{RSN}} + G_{2-4S} \cdot (Z_L + 2R_F + 2R_P)}$$

For applications where $Z_T/(\alpha_{RSN} \cdot G_{2\text{-}4S}) + 2R_F + 2R_P$ is chosen to be equal to Z_L the expression for $G_{4\text{-}2}$ simplifies to:

$$G_{4-2} = -\frac{Z_T}{Z_{RX}} \cdot \frac{1}{2G_{2-4S}}$$

Four-Wire to Four-Wire Gain

From (1), (2) and (3) with $E_L = 0$:

$$G_{4-4} = \frac{V_{TX}}{V_{RX}} = -\frac{Z_T}{Z_{RX}} \cdot \frac{G_{2-4S} \cdot (Z_L + 2R_F + 2R_P)}{\frac{Z_T}{\alpha_{RSN}} + G_{2-4S} \cdot (Z_L + 2R_F + 2R_P)}$$

Hybrid Function

The hybrid function can easily be implemented utilizing the uncommitted amplifier in conventional CODEC/filter combinations. Please, refer to figure 9. Via impedance Z_B a current proportional to V_{RX} is injected into the summing node of the combination CODEC/filter amplifier. As can be seen from the expression for the four-wire to four-wire gain a voltage proportional to V_{RX} is returned to V_{TX}. This voltage is converted by R_{TX} to a current flowing into the same summing node. These currents can be made to cancel by letting:

$$\frac{V_{TX}}{R_{TX}} + \frac{V_{RX}}{Z_B} = 0 (E_L = 0)$$

The four-wire to four-wire gain, $G_{4\text{-}4}$, includes the required phase shift and thus the balance network Z_B can be calculated from:

$$Z_B = -R_{TX} \cdot \frac{V_{RX}}{V_{TX}} = R_{TX} \cdot \frac{Z_{RX}}{Z_T} \cdot \frac{\frac{Z_T}{\alpha_{RSN}} + G_{2-4S} \cdot (Z_L + 2R_F + 2R_P)}{G_{2-4S} \cdot (Z_L + 2R_F + 2R_P)}$$

When choosing R_{TX}, make sure the output load of the VTX terminal is >20 kΩ.

If calculation of the Z_B formula above yields a balance network containing an inductor, an alternate method is recommended. Contact Ericsson Microelectronics for assistance.

The PBL 386 30/2 SLIC may also be used together with programmable CODEC/filters. The programmable CODEC/filter allows for system controller adjustment of hybrid balance to accommodate different line impedances without change of hardware. In addition, the transmit and receive gain may be adjusted. Please, refer to the programmable CODEC/filter data sheets for design information.

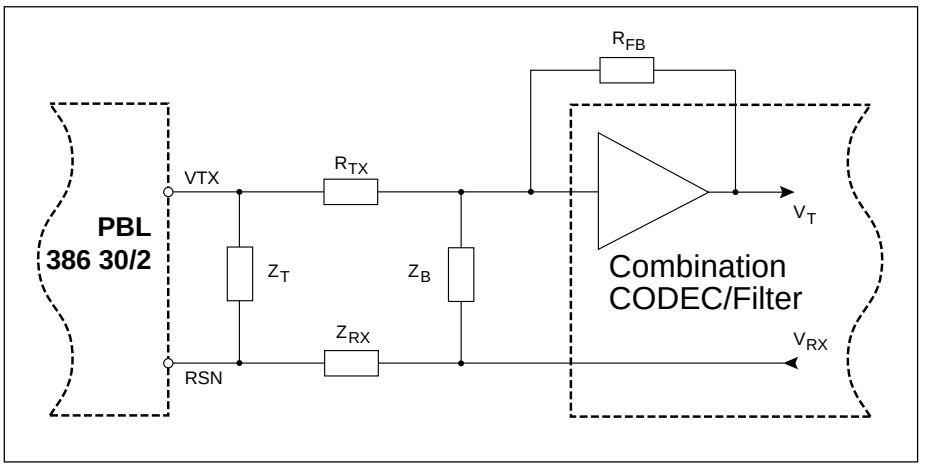


Figure 9. Hybrid function.

Longitudinal Impedance

A feed back loop counteracts longitudinal voltages at the two-wire port by injecting longitudinal currents in opposing phase.

Thus longitudinal disturbances will appear as longitudinal currents and the TIPX and RINGX terminals will experience very small longitudinal voltage excursions, leaving metallic voltages well within the SLIC common mode range.

The SLIC longitudinal impedance per wire, Z_{LoT} and Z_{LoR}, appears as typically 20Ω to longitudinal disturbances. It should be noted that longitudinal currents may exceed the dc loop current without disturbing the vf transmission.

Capacitors C_{TC} and C_{RC}

The capacitors designated C_{TC} and C_{RC} in figure 11, connected between TIPX and ground as well as between RINGX and ground, can be used for RFI filtering. The recommended value for C_{TC} and C_{RC} is 2200 pF. Higher capacitance values may be used, but care must be taken to prevent degradation of either longitudinal balance or return loss. C_{TC} and C_{RC} contribute to a metallic impedance of $1/(\pi \cdot f \cdot C_{TC}) = 1/(\pi \cdot f \cdot C_{RC})$, a TIPX to ground impedance of $1/(2 \cdot \pi \cdot f \cdot C_{TC})$ and a RINGX to ground impedance of $1/(2 \cdot \pi \cdot f \cdot C_{RC})$.

AC - DC Separation Capacitor, C_{HP}

The high pass filter capacitor connected between terminals HP and TIPX provides the separation of the ac signal from the dc part. C_{HP} positions the low end frequency response break point of the ac loop in the SLIC. Refer to table 1 for recommended values of C_{HP}.

Example: A C_{HP} value of 150 nF will position the low end frequency response 3dB break point of the ac loop at 1,8 Hz (f_{3dB}) according to $f_{3dB} = 1/(2 \cdot \pi \cdot R_{HP} \cdot C_{HP})$ where R_{HP} = 600 kΩ.

High-Pass Transmit Filter

The capacitor C_{TX} in figure 11 connected between the VTX output and the CODEC/filter forms, together with R_{TX} and/or the input impedance of a programmable CODEC/filter, a high-pass RC filter. It is recommended to position the 3 dB break point of this filter between 30 and 80 Hz to get a faster response for the dc steps that may occur at DTMF signalling.

Capacitor C_{LP}

The capacitor C_{LP}, which connects between the terminals CLP and VBAT, positions together with the resistive loop feed resistor R_{SG} (see section Battery Feed), the high end frequency break point of the low pass filter in the dc loop in the SLIC. C_{LP} together with R_{SG}, C_{HP} and Z_T (see section Two-Wire Impedance) forms the total two wire output impedance of the SLIC. The choise of these programmable components have an influence on the power supply rejection ratio (PSRR) from VBAT to the two wire side at sub-audio frequencies. At these frequencies capacitor C_{LP} also influences the transversal to longitudinal balance in the SLIC. Table 1 suggests suitable values on C_{LP} for different feeding characteristics. Typical values of the transversal to longitudinal balance (T-L bal.) at 200Hz is given in table 1 for the chosen values on C_{LP}.

R_{Feed} [Ω]	R_{SG} [kΩ]	C_{LP} [nF]	T-L bal. @200Hz [dB]	C_{HP} [nF]
2·50	0	150	-46	47
2·200	60,4	100	-46	150
2·400	147	47	-43	150
2·800	301	22	-36	150

Table 1. R_{SG}, C_{LP} and C_{HP} values for different feeding characteristics.

Battery Feed

The PBL 386 30/2 SLIC emulate resistive loop feed, programmable between 2·50 Ω and 2·900 Ω, with adjustable current limitation. In the current limited region the loop current has a slight slope corresponding to 2·30 kΩ, see figure 12 reference B.

The open loop voltage measured between the TIPX and RINGX terminals is tracking the battery voltage V_{Bat}. The signalling headroom, or overhead voltage V_{TRO}, is programmable with a resistor R_{OV} connected between terminal POV on the SLIC and ground. Please refer to section "Programmable overhead voltage(POV)".

The battery voltage overhead, V_{OH}, depends on the programmed signal overhead voltage. V_{OH} defines the TIP to RING voltage at open loop conditions according to V_{TR}(at I_L = 0 mA) = $|V_{Bat}|$ - V_{OH}.

Refer to table 2 for typical values on V_{OH} and V_{OHVirt}. The overhead voltage is changed when the line current is approaching open loop conditions. To ensure maximum open loop voltage, even with a leaking telephone line, this occurs at a line current of approximately 6 mA. When the overhead voltage has changed, the line voltage is kept nearly constant with a steep slope corresponding to 2·25 Ω(reference G in figure 12).

The virtual battery overhead, V_{OHvirt}, is defined as the difference between the battery voltage and the crossing point of all possible resistive feeding slopes, see figure 12 reference J. The virtual battery overhead is a theoretical constant needed to be able to calculate the feeding characteristics.

SLIC	*$V_{OH(typ)}$ (V)*	*$V_{OHvirt(typ)}$ (V)*
PBL 386 30/2	3.0 +V_{TRO}	4.9 +V_{TRO}

Table 2. Battery overhead.

The resistive loop feed (reference D in figure 12) is programmed by connecting a resistor, R_{SG}, between terminals PSG and VBAT according to the equation:

$$R_{Feed} = \frac{R_{SG} + 2 \cdot 10^4}{200} + 2R_F$$

where R_{Feed} is in Ω for R_{SG} and R_F in Ω.

The current limit (reference C in figure 12) is adjusted by connecting a resistor, R_{LC}, between terminal PLC and ground according to the equation:

$$R_{LC} = \frac{1000}{I_{LProg} + 4}$$

where R_{LC} is in kΩ for I_{LProg} in mA.

A second, lower battery voltage may be connected to the device at terminal VBAT2 to reduce short loop power dissipation. The SLIC automatically switches between the two battery supply voltages without need for external control. The silent battery switching occurs when the line voltage passes the value
|VB2| - 40·I_L - (V_{OHVirt} -1,3), if I_L > 6mA.

For correct functionality it is important to connect the terminal VBAT2 to the second power supply via the diode D_{VB2} in figure 11.

An optional diode D_{BB} connected between terminal VB and the VB2 power supply, see figure 11, will make sure that the SLIC continues to work on the second battery even if the first battery voltage disappears.

If a second battery voltage is not used, VBAT2 is connected to VBAT on the SLIC and C_{VB2}, D_{BB} and D_{VB2} are removed.

Metering applications

For designs with metering applications please contact Ericsson Microelectronics for assistance.

CODEC Receive Interface

The PBL 386 30/2 SLIC have got a completely new receive interface at the four wire side which makes it possible to reduce the number of capacitors in the applications and to fit both single and dual battery feed CODECs. The RSN terminal, connecting to the CODEC receive output via the resistor R_{RX}, is dc biased with +1,25V. This makes it possible to compensate for currents floating due to dc voltage differences between RSN and the CODEC output without using any capacitors. This is done by connecting a resistor R_R between the RSN terminal and ground. With current directions defined as in figure 13, current summation gives:

$$-I_{RSN} = I_{RT} + I_{RRX} + I_{RR} =$$

$$\frac{1{,}25}{R_T} + \frac{1{,}25 - V_{CODEC}}{R_{RX}} + \frac{1{,}25}{R_R}$$

where V_{CODEC} is the reference voltage of the CODEC at the receive output.
From this equation the resistor R_R can be calculated as

$$R_R = \frac{1{,}25}{-I_{RSN} - \frac{1{,}25}{R_T} - \frac{1{,}25 - V_{CODEC}}{R_{RX}}}$$

For values on I_{RSN}, see table 3.
The resistor R_R has no influence on the ac transmission.

SLIC	*I_{RSN} [μA]*
PBL 386 30/2	-55

Table 3. The SLIC internal bias current with the direction of the current defined as positive when floating into the terminal RSN.

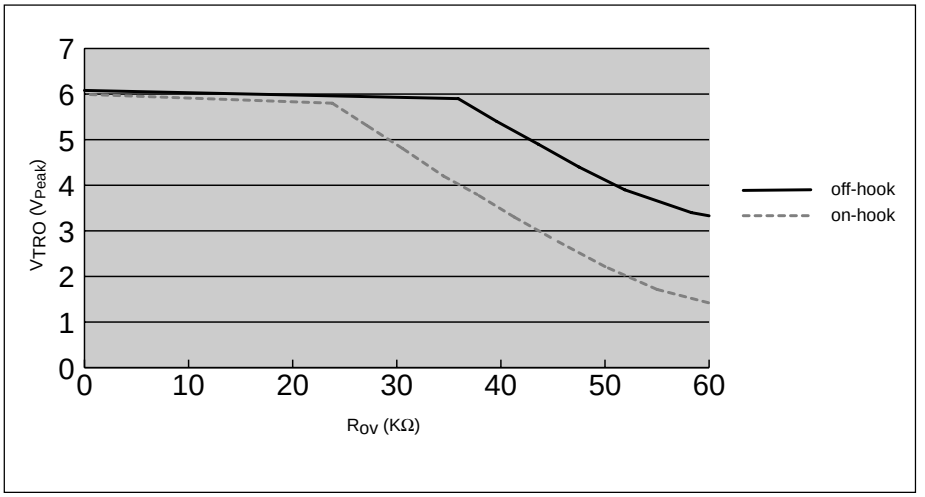
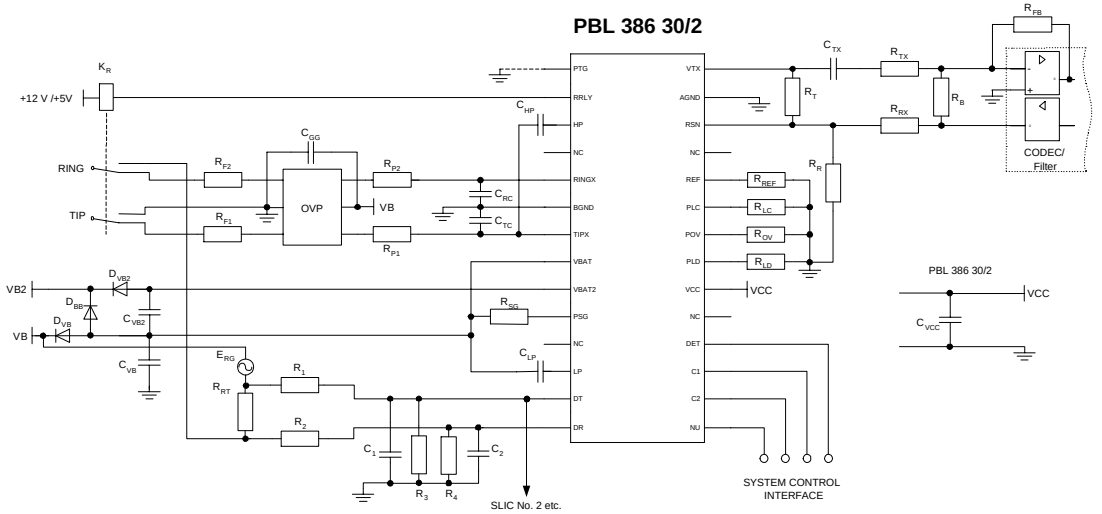


Figure 10. Programmable overhead voltage (POV). R_L = 600 Ω or ∞.



RESISTORS: (Values according to IEC E96 series)

R_{SG}	= 0 Ω	1% 1/10 W
R_{LD}	= 49,9 kΩ	1% 1/10 W
R_{OV}	= User programmable	
R_{LC}	= 32,4 kΩ	1% 1/10 W
R_{REF}	= 49,9 kΩ	1% 1/10 W
R_R	= 64,9 kΩ	1% 1/10 W
R_T	= 105 kΩ	1% 1/10 W
R_{TX}	= 24,9 kΩ	1% 1/10 W
R_B	= 22,1 kΩ	1% 1/10 W
R_{RX}	= 52,3 kΩ	1% 1/10 W
R_{FB}	Depending on CODEC / filter	
R_1	= 604 kΩ	1% 1/10 W
R_2	= 604 kΩ	1% 1/10 W
R_3	= 249 kΩ	1% 1/10 W
R_4	= 280 kΩ	1% 1/10 W
R_{RT}	= 330 Ω	5% 2 W
R_{F1}, R_{F2}	= Line resistor, 40 Ω 1% match	
R_{P1}, R_{P2}	= 10 Ω	1% 1/10 W,(Note 1)

CAPACITORS: (Values according to IEC E96 series)

C_{VB}	= 100 nF	100 V 10%
C_{VB2}	= 150 nF	100 V 10%
C_{VCC}	= 100 nF	10 V 10%
C_{TC}	= 2,2 nF	100 V 10%
C_{RC}	= 2,2 nF	100 V 10%
C_{HP}	= 47 nF	100 V 10%
C_{LP}	= 150 nF	100 V 10%
C_{TX}	= 100 nF	10 V 10%
C_{GG}	= 220 nF	100 V 10%
C_1	= 330 nF	63 V 10%
C_2	= 330 nF	63 V 10%

DIODES:

D_{VB}	= 1N4448
D_{VB2}	= 1N4448
D_{BB}	= 1N4448

OVP:
Secondary protection (e. g. Power Innovations TISPPBL2). The ground terminals of the secondary protection should be connected to the common ground on the Printed Board Assembly with a track as short and wide as possible, preferable a groundplane.

NOTE:

1. R_{P1} and R_{P2} may be omitted if D_{VB} is in place.

Figure 11. Single-channel subscriber line interface with PBL 386 30/2 and combination CODEC/filter.

Programmable overhead voltage(POV)

With the POV function the overhead voltage can be increased.

If the POV pin is left open the overhead voltage is internally set to 3,2 V_{Peak} in off-hook and 1,3 V_{Peak} on-hook. If a resistor R_{OV} is connected between the POV pin and AGND, the overhead voltage can be set to higher values, typical values can be seen in figure 10. The R_{OV} and corresponding V_{TRO} (signal headroom) are typical values for THD <1% and the signal frequency 1000Hz.

Observe that the 4-wire output terminal V_{TX} can not handle more than 3,2 $V_{Peak.}$ So if the gain 2-wire to 4-wire is 0dB, 3,2 V_{Peak} is maximum also for the 2-wire side. Signal levels between 3,2 and 6,4 V_{Peak} on the 2-wire side can be handled with the PTG shorted so that the gain $G_{2\text{-}4S}$ become -6,02dB. Please note that the two-wire impedance, R_R and the 4-wire to 4-wire gain has to be recalculated if the PTG is shorted.

Please note that the maximum signal current at the 2-wire side can not be greater than 9 mA.

How to use POV:

1. Decide what overhead voltage(V_{TRO}) is needed. The POV function is only needed if the overhead voltage exceeds 3,2 V_{Peak}
2. In figure 10 the corresponding R_{OV} for the decided V_{TRO} can be found.
3. If the overhead voltage exceeds 3,2 V_{Peak}, the $G_{2\text{-}4S}$ gain has to be changed to -6,02dB by connecting the PTG pin to AGND. Please note that the two-wire impedance, R_R and the 4-wire to 4-wire gain has to be recalculated.

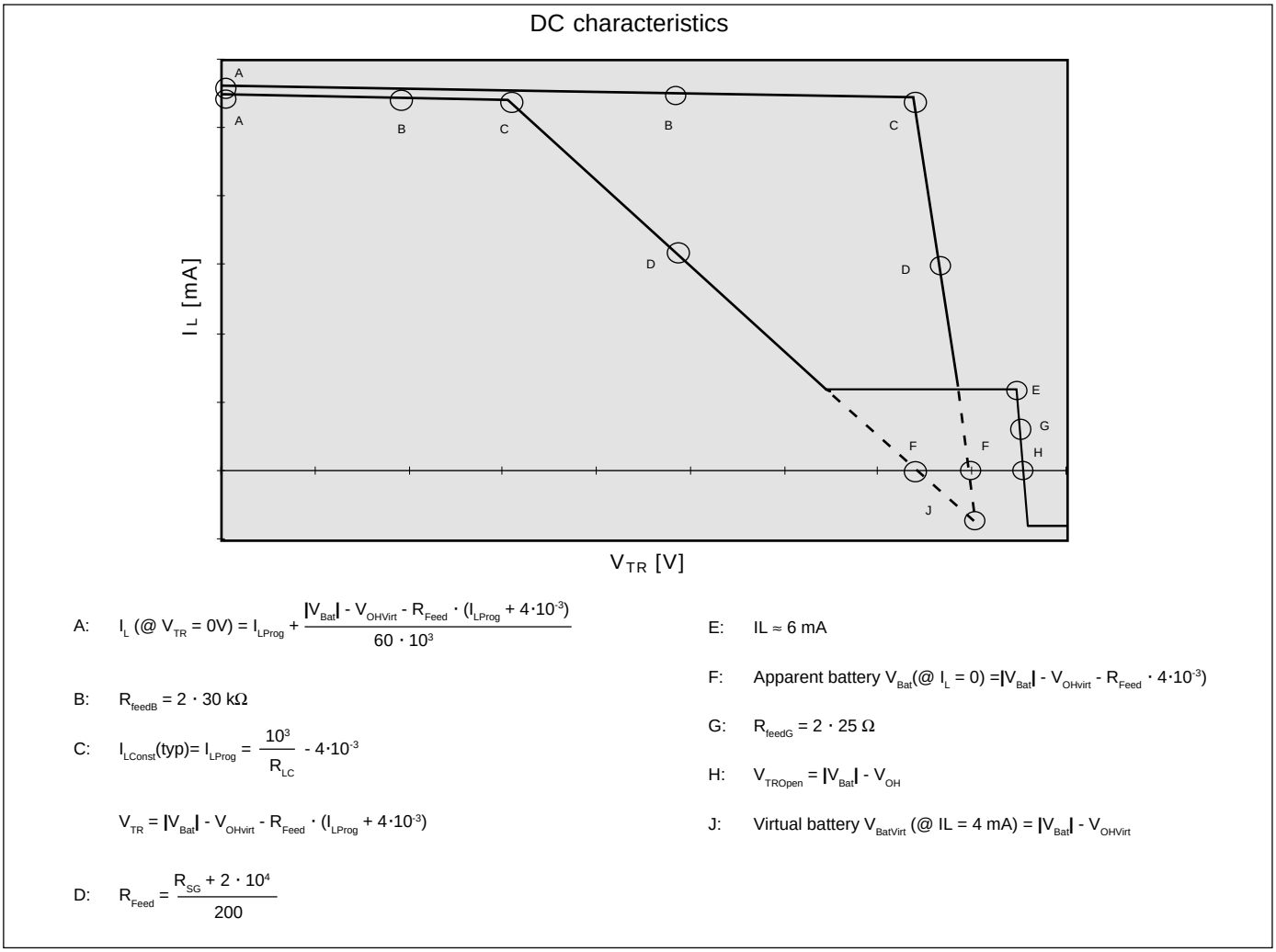


Figure 12. Battery feed characteristics (without the protection resistors on the line).

Analog Temperature Guard

The widely varying environmental conditions in which SLICs operate may lead to the chip temperature limitations being exceeded. The PBL 386 30/2 SLIC reduce the dc line current when the chip temperature reaches approximately 145°C and increases it again automatically when the temperature drops. Accordingly transmission is not lost under high ambient temperature conditions.

The detector output, DET, is forced to a logic low level when the temperature guard is active.

Loop Monitoring Functions

The loop current and ring trip detector report their status through a common output, DET. The detector to be connected to DET is selected via the two bit wide control interface C1 and C2. Please refer to section Control Inputs for a description of the control interface.

Loop Current Detector

The loop current detector is indicating that the telephone is off hook and that current is flowing in the loop by putting the output DET to a logical low level when selected.The loop current threshold value, I_{LTh}, at which the loop current detector changes state is programmable by selecting the value of resistor R_{LD}. R_{LD} connects between pin PLD and ground and is calculated according to

$$R_{LD} = \frac{500}{I_{LTh}}$$

The current detector is internally filtered and is not influenced by the ac signal at the two wire side.

Ring Trip Detector

Ring trip detection is accomplished by connecting an external network to a comparator in the SLIC with inputs DT and DR. The ringing source can be balanced or unbalanced superimposed on V_B or GND. The unbalanced ringing source may be applied to either the ring lead or the tip lead with return via the other wire. A ring relay driven by the SLIC ring relay driver connects the ringing source to tip and ring.

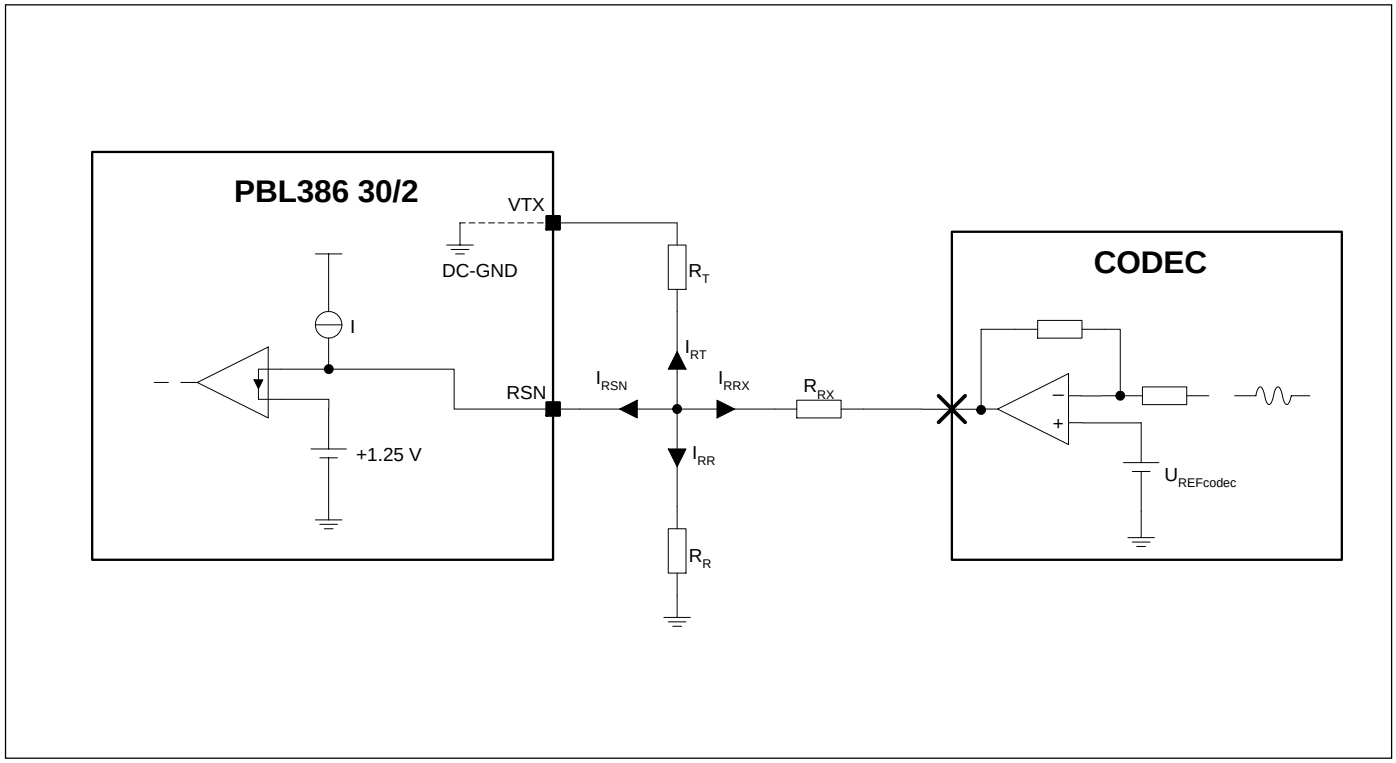


Figure 13. CODEC receive interface.

The ring trip function is based on a polarity change at the comparator input when the line goes off-hook. In the on-hook state no dc current flows through the loop and the voltage at comparator input DT is more positive than the voltage at input DR. When the line goes off-hook, while the ring relay is energized, dc current flows and the comparator input voltage reverses polarity.

Figure 11 gives an example of a ring trip detection network. This network is applicable, when the ring voltage is superimposed on V_B and is injected on the ring lead of the two-wire port. The dc voltage across sense resistor R_{RT} is monitored by the ring trip comparator input DT and DR via the network R_1, R_2, R_3, R_4, C_1 and C_2. With the line on-hook (no dc current) DT is more positive than DR and the DET output will report logic level high, i.e. the detector is not tripped. When the line goes off-hook, while ringing, a dc current will flow through the loop including sense resistor R_{RT} and will cause input DT to become more negative than input DR. This changes output DET to logic level low, i.e. tripped detector condition. The system controller (or line card processor) responds by de-energizing the ring relay, i.e. ring trip.

Complete filtering of the 20 Hz ac component at terminal DT and DR is not necessary. A toggling DET output can be examined by a software routine to deter-mine the duty cycle. When the DET output is at logic level low for more than half the time, off-hook condition is indicated.

Relay driver

The PBL 386 30/2 SLIC incorporates a ring relay driver designed as open collector (npn) with a current sinking capability of 50 mA. The drive transistor emitter is connected to BGND. The relay driver has an internal zener diode clamp for inductive kick-back voltages. Care must be taken when using the relay driver together with relays that have high impedance.

Control Inputs

The PBL 386 30/2 SLIC have two digital control inputs, C1 and C2.

A decoder in the SLIC interprets the control input condition and sets up the commanded operating state.
C1 and C2 are internal pull-up inputs.

Open Circuit State

In the Open Circuit State the TIPX and RINGX line drive amplifiers as well as other circuit blocks are powered down. This causes the SLIC to present a high impedance to the line. Power dissipation is at a minimum and no detectors are active.

Ringing State

The ring relay driver and the ring trip detector are activated and the ring trip detector is indicating off hook with a logic low level at the detector output.
The SLIC is in the active normal state.

Active State

TIPX is the terminal closest to ground and sources loop current while RINGX is the more negative terminal and sinks loop current. Vf signal transmission is normal and the loop current detector is activated. The loop current detector is indicating off hook with a logic low level present at the detector output.

Overvoltage Protection

The PBL 386 30/2 SLIC must be protected against overvoltages on the telephone line caused by lightning, ac power contact and induction. Refer to Maximum Ratings, TIPX and RINGX terminals, for maximum allowable continuous and transient currents that

may be applied to the SLIC.

Secondary Protection

The circuit shown in figure 11 utilizes series resistors together with a programmable overvoltage protector
(e.g. Power Innovations TISPPBL2), serving as a secondary protection.

The TISPPBL2 is a dual forward-conducting buffered p-gate overvoltage protector. The protector gate references the protection (clamping) voltage to negative supply voltage (i e the battery voltage, V_B). As the protection voltage will track the negative supply voltage the overvoltage stress on the SLIC is minimized.

Positive overvoltages are clamped to ground by a diode. Negative overvoltages are initially clamped close to the SLIC negative supply rail voltage and the protector will crowbar into a low voltage on-state condition, by firing an internal thyristor.

A gate decoupling capacitor, C_{GG}, is needed to carry enough charge to supply a high enough current to quickly turn on the thyristor in the protector. C_{GG} shall be placed close to the overvoltage protection device. Without the capacitor even the low inductance in the track to the V_{Bat} supply will limit the current and delay the activation of the thyristor clamp.

The fuse resistors R_F serve the dual purposes of being non- destructive energy dissipators, when transients are clamped and of being fuses, when the line is exposed to a power cross.

If a PTC is chosen for R_F, note that it is important to always use PTC´s in series with resistors not sensitive to temperature, as the PTC will act as a capacitance for fast transients and therefore will not protect the SLIC.

Power-up Sequence

No special power-up sequence is necessary except that ground has to be present before all other power supply voltages.

Printed Circuit Board Layout

Care in PCB layout is essential for proper function. The components connecting to the RSN input should be placed in close proximity to that pin, so that no interference is injected into the RSN pin. Ground plane surrounding the RSN pin is advisable.

Analog ground (AGND) should be connected to battery ground (BGND) on the PCB in one point.

The capacitors for the battery should be connected with short wide leads of the same length.

Ordering Information

Package	Temp. Range	Part No.
24 pin SSOP Tape & Reel	-40° - +85° C	PBL 386 30/2SHT
24 pin SOIC Tube	-40° - +85° C	PBL 386 30/2SOS
24 pin SOIC Tape & Reel	-40° - +85° C	PBL 386 30/2SOT
28 pin PLCC Tube	-40° - +85° C	PBL 386 30/2QNS
28 pin PLCC Tape & Reel	-40° - +85° C	PBL 386 30/2QNT

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ERICSSON

Ericsson Microelectronics AB
SE-164 81 Kista-Stockholm, Sweden
Telephone: +46 8 757 50 00